

IGBT

TRENCHSTOP™ IGBT4 High Power Chip
IGC142T120T8RH

Data Sheet

Industrial Power Control



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TRENCHSTOP™ IGBT4 High Power Chip

Features:

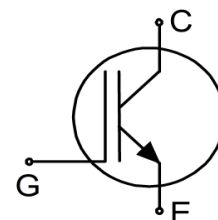
- 1200V trench & field stop technology
- LOW V_{CEsat}
- Soft turn off
- Positive temperature coefficient
- Easy paralleling

Recommended for:

- Medium / high power modules

Applications:

- Medium / high power drives



Chip Type	V_{CE}	I_{Cn}	Die Size	Package
IGC142T120T8RH	1200V	150A	11.31mm x 12.56mm	Sawn on foil

Mechanical Parameters

Die size	11.31 x 12.56		mm ²
Emitter pad size	See chip drawing		
Gate pad size	1.31 x 0.811		
Area total	142.05		
Silicon thickness	140		μm
Wafer size	200		mm
Maximum possible chips per wafer	170		
Passivation frontside	Photoimide		
Pad metal	3200nm AlSiCu		
Backside metal	Ni Ag – system To achieve a reliable solder connection it is strongly recommended not to consume the Ni layer completely during production process		
Die bond	Electrically conductive epoxy glue and soft solder		
Wire bond	Al, ≤500μm		
Reject ink dot size	Ø 0.65mm; max. 1.2mm		
Storage environment (<6 months)	for original and sealed MBB bags	Ambient atmosphere air, temperature 17°C – 25°C	
	for open MBB bags	Acc. IEC62258-3; Section 9.4 Storage Environment.	

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage, $T_{vj}=25^{\circ}\text{C}$	V_{CE}	1200	V
DC collector current, limited by $T_{vj\text{ max}}^1$	I_C	-	A
Pulsed collector current, t_p limited by $T_{vj\text{ max}}^2$	$I_{C,puls}$	450	A
Gate-emitter voltage	V_{GE}	± 20	V
Virtual junction operating temperature	T_{vj}	-40 ... +175	$^{\circ}\text{C}$
Short circuit data ^{1/2/3} $V_{GE}=15\text{V}$, $V_{CC}=800\text{V}$, $T_{vj}=150^{\circ}\text{C}$	t_{sc}	10	μs

Static Characteristics (tested on wafer), $T_{vj}=25^{\circ}\text{C}$

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0\text{V}$, $I_C=5.7\text{mA}$	1200	-	-	V
Collector-emitter saturation voltage	V_{CEsat}	$V_{GE}=15\text{V}$, $I_C=45\text{A}$	0.97	1.1	1.26	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C=5.7\text{mA}$, $V_{GE}=V_{CE}$	5.1	5.8	6.4	
Zero gate voltage collector current	I_{CES}	$V_{CE}=1200\text{V}$, $V_{GE}=0\text{V}$	-	-	20	μA
Gate-emitter leakage current	I_{GES}	$V_{CE}=0\text{V}$, $V_{GE}=20\text{V}$	-	-	120	nA
Integrated gate resistor	r_G		-	5	-	Ω

Electrical Characteristics ²

Parameter	Symbol	Conditions	Value			Unit	
			min.	typ.	max.		
Collector-emitter saturation voltage	V_{CEsat}	$V_{GE}=15\text{V}$, $I_C=150\text{A}$	$T_{vj}=25^{\circ}\text{C}$	-	1.7	-	V
			$T_{vj}=150^{\circ}\text{C}$	-	2.1	-	
Input capacitance	C_{ies}	$V_{CE}=25\text{V}$, $V_{GE}=0\text{V}$, $f=1\text{MHz}$ $T_{vj}=25^{\circ}\text{C}$	-	9300	-	pF	
Reverse transfer capacitance	C_{res}		-	510	-		

¹ Depending on thermal properties of assembly.

² Not subject to production test - verified by design/characterization.

³ Allowed number of short circuits: <1000; time between short circuits: >1s.



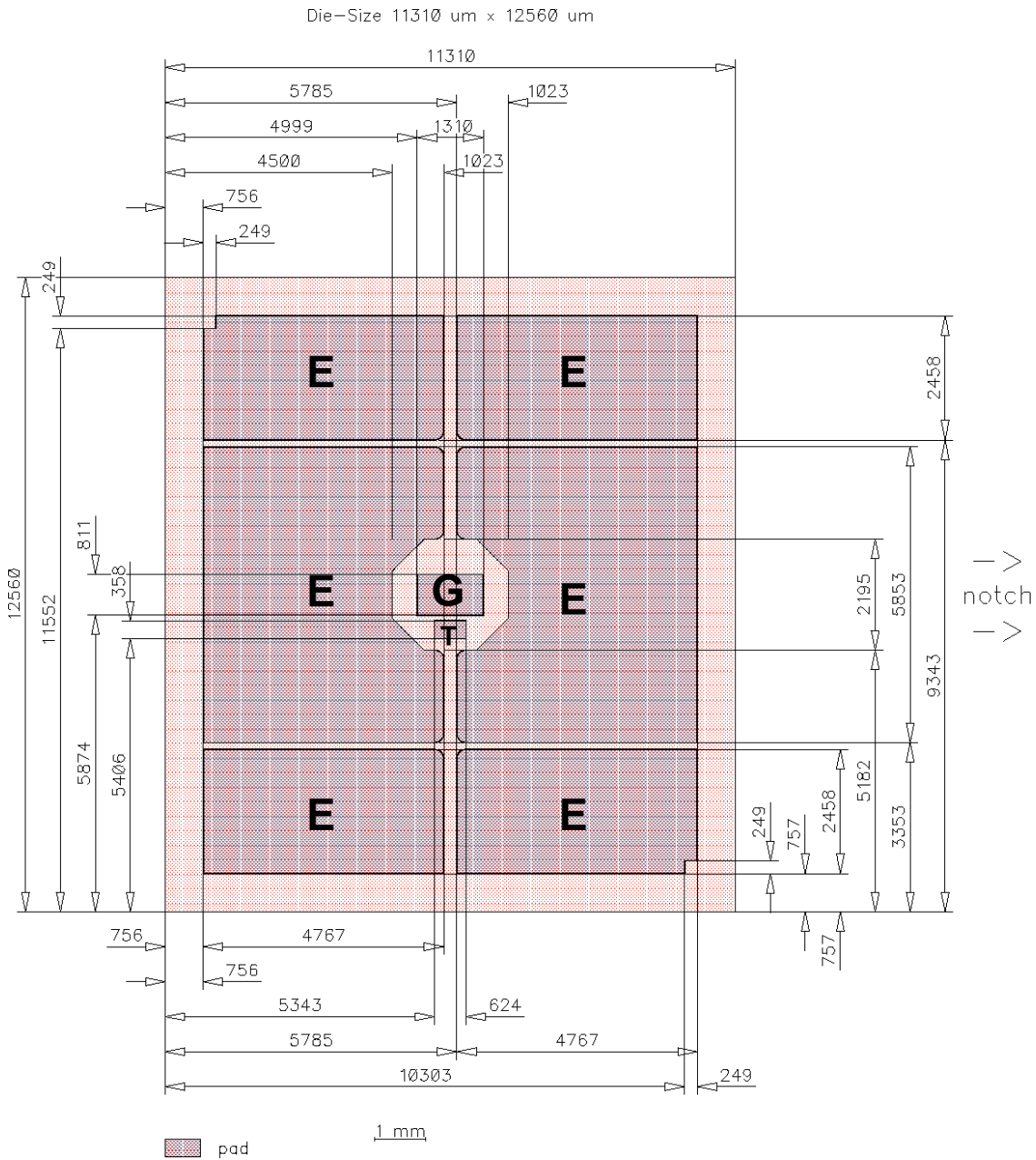
IGC142T120T8RH

Further Electrical Characteristics

Switching characteristics and thermal properties are depending strongly on module design and mounting technology and can therefore not be specified for a bare die.

Application example	FZ600R12KP4	Rev. 2.2
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Chip Drawing



E = Emitter

G = Gate

T = Test pad do not contact



IGC142T120T8RH

Bare Die Product Specifics

Test coverage at wafer level cannot cover all application conditions. Therefore it is recommended to test all characteristics which are relevant for the application at package level, including RBSOA and SCSOA.

Description

AQL 0.65 for visual inspection according to failure catalogue

Electrostatic Discharge Sensitive Device according to MIL-STD 883

Revision History

Revision	Subjects (major changes since last revision)	Date
2.0	Final data sheet	11.05.2016

Relevant Application Notes

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